

SOT624-1

plastic thermal enhanced ball grid array package; 1312 balls;
body 40 x 40 x 1.65 mm; heatsink

8 February 2016

Package information

1. Package summary

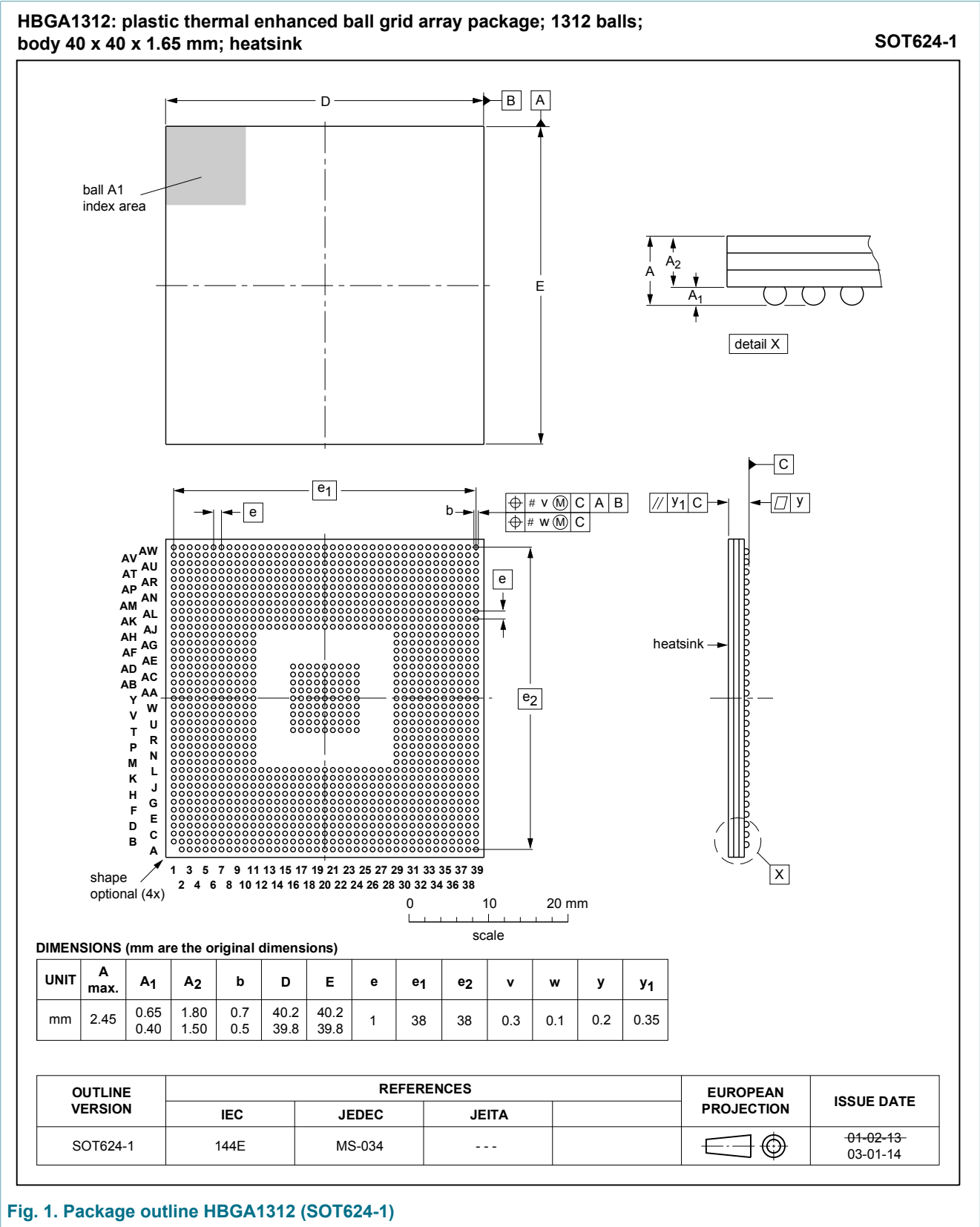
Terminal position code	B (bottom)
Package type descriptive code	HBGA1312
Package type industry code	HBGA1312
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	14-1-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		39.8	-	40	40.2	mm
E	package width		39.8	-	40	40.2	mm
A	seated height		[tbd]	-	2.45	2.45	mm
A ₂	package height		1.5	-	1.65	1.8	mm
n ₂	actual quantity of termination		-	-	1312	-	



2. Package outline



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3. Soldering

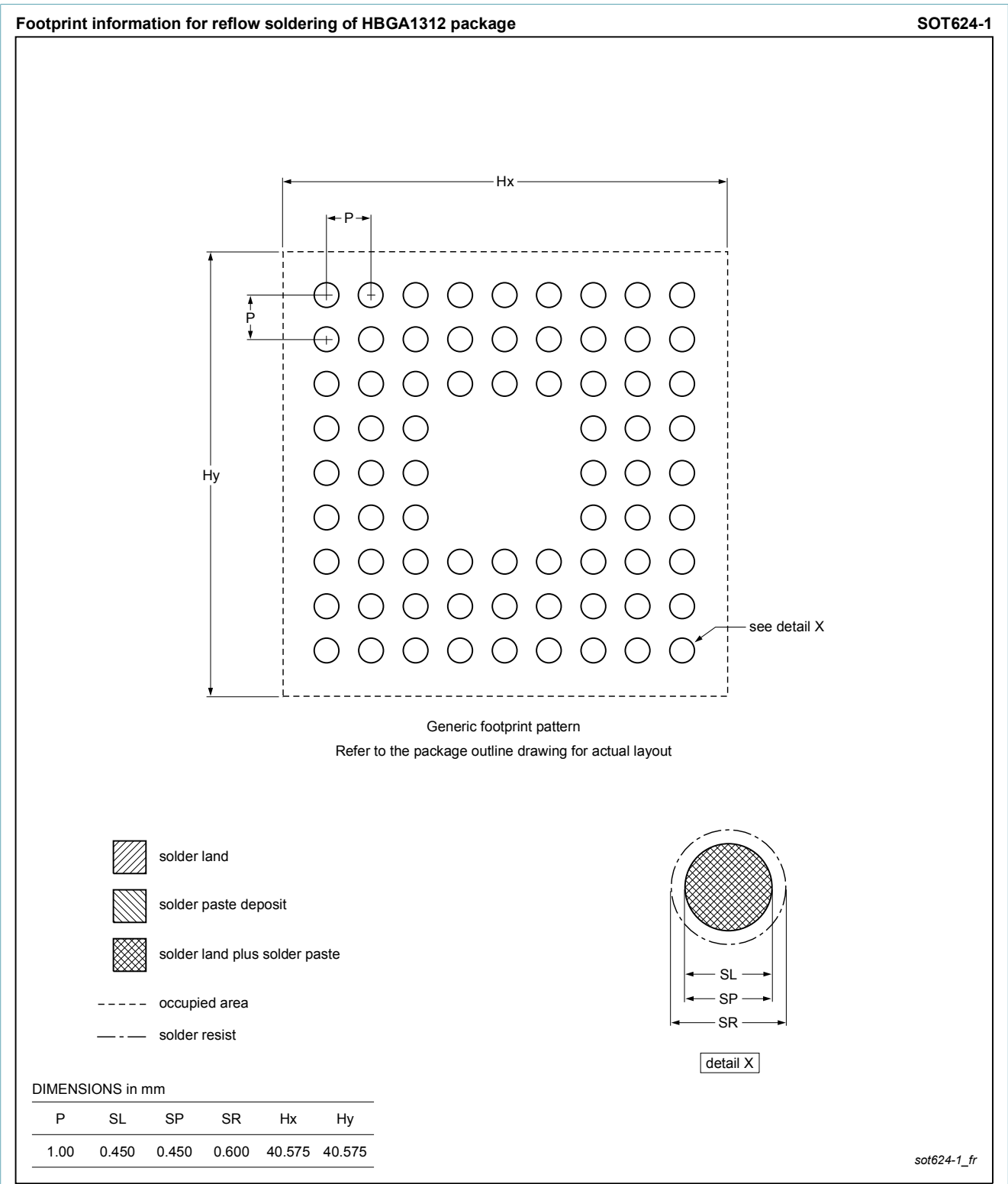


Fig. 2. Reflow soldering footprint for HBGA1312 (SOT624-1)

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4. Legal information

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